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Attorney Docket No. 95-553-US

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

GROUP 3200

Title of the Invention:

PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME

Inventors: ELDRIDGE, et al.

Filing Date: November 9, 1995

Serial Number: 08/554,902

SUPPLEMENTAL INFORMATION DISCLOSURE CITATION

(Substitute PTO-1449)

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION is being submitted **prior to an action on the merits.**

NO FEE IS REQUIRED.

Charge any shortfall to Dep. Acct. 12-1445.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION (5) is being provided in addition to:

- (1) INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (2) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (3) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
- (4) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96

Although not required, TITLES for the patent references are provided herewith, as an aid to the examiner.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION lists references cited in the International Search Reports pertaining to various commonly-owned, copending PCT applications. All the references listed in the Search Reports are listed herein. However, if the references have previously been disclosed, only the patent number is listed.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION also lists references which recently have come to the applicant's attention.

The references presented herein are arranged in "groups", as follows:

GROUP 1. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14909 filed 13 Nov 95.

 copies of these references are enclosed herewith,
except for copies of references previously submitted to
the Patent Office;

x copies of these references are NOT enclosed herewith,
but have (i) previously been disclosed or (ii) may be
found in the file of commonly-owned, copending U.S.
Patent Application No. 08/452,255, filed 5/26/95

GROUP 2. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14843 filed 13 Nov 95.

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Patent Application No. 08/526,246, filed 9/21/95

GROUP 3. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14842 filed 13 Nov 95.

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but have (i) previously been disclosed or (ii) may be
found in the file of commonly-owned, copending U.S.
Patent Application No. 08/533,584, filed 10/18/95

GROUP 4. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14844 filed 13 Nov 95.

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the Patent Office;

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but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/554,902, filed 11/9/95

GROUP 5. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending PCT/US95/14885 filed 15 Nov 95.

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x copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/558,332, filed 11/15/95

GROUP 6. References which recently have come to the attention of the applicant.

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x copies of these references are NOT enclosed herewith, but may be found in the file of commonly-owned, copending U.S. Patent Application No. 08/340,144, filed 11/15/94

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GROUP 1: PCT/US95/14909 filed 13 Nov 95

5,037,023 Akiyama, et al.; 8/91 228/102
METHOD AND APPARATUS FOR WIREBONDING

5,210,939 Mallik, et al.; 5/93 29/840
LEAD GRID ARRAY INTEGRATED CIRCUIT

4,659,437 Shiba, et al.; 4/87 204/28
METHOD OF THERMAL DIFFUSION ALLOY PLATING FOR STEEL WIRE
ON CONTINUOUS BASIS

5,309,324 Hernandez, et al.; 5/94 361/734
DEVICE FOR INTERCONNECTING INTEGRATED CIRCUIT PACKAGES TO
CIRCUIT BOARDS

5,045,975 Cray, et al.; 9/91 361/412
THREE DIMENSIONALLY INTERCONNECTED MODULE ASSEMBLY

3,753,665 McCary, et al.; 8/73 29/191.6
MAGNETIC FILM PLATED WIRE

3,844,909 McCary, et al.; 10/74 204/40
MAGNETIC FILM PLATED WIRE AND SUBSTRATES THEREFOR

4,998,885 Beaman; 3/91 439/66
ELASTOMERIC AREA ARRAY INTERPOSER

JAP 3-142847 (64-279696); 10/89
SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

5,067,007 previously disclosed to PTO
5,110,032 previously disclosed to PTO
5,189,507 previously disclosed to PTO
5,317,479 previously disclosed to PTO
4,295,700 previously disclosed to PTO
4,764,848 previously disclosed to PTO
3,842,189 previously disclosed to PTO
4,667,219 previously disclosed to PTO
4,793,814 previously disclosed to PTO
4,751,199 previously disclosed to PTO
4,732,313 previously disclosed to PTO

GROUP 2: PCT/US95/14843 filed 13 Nov 95

5,386,344 previously disclosed to PTO
5,366,380 previously disclosed to PTO
5,317,479 previously disclosed to PTO
5,299,939 previously disclosed to PTO
5,189,507 previously disclosed to PTO
5,130,779 previously disclosed to PTO
5,110,032 previously disclosed to PTO
5,095,187 previously disclosed to PTO
5,086,337 previously disclosed to PTO
5,067,007 previously disclosed to PTO
4,989,069 previously disclosed to PTO
4,955,523 previously disclosed to PTO
4,914,814 previously disclosed to PTO
4,893,172 previously disclosed to PTO
4,860,433 previously disclosed to PTO
4,821,148 previously disclosed to PTO
4,793,814 previously disclosed to PTO
4,777,564 previously disclosed to PTO
4,764,848 previously disclosed to PTO
4,705,205 previously disclosed to PTO
4,667,219 previously disclosed to PTO

4,642,889	previously disclosed to PTO
4,532,152	previously disclosed to PTO
4,418,857	previously disclosed to PTO
4,330,165	previously disclosed to PTO
4,295,700	previously disclosed to PTO
4,067,104	previously disclosed to PTO
3,795,037	previously disclosed to PTO
3,616,532	previously disclosed to PTO
3,509,270	previously disclosed to PTO
3,460,238	previously disclosed to PTO
3,373,481	previously disclosed to PTO

GROUP 3: PCT/US95/14842 filed 13 Nov 95

5,045,975 Cray, et al.; 9/91 361/412
THREE DIMENSIONALLY INTERCONNECTED MODULE ASSEMBLY

5,317,479	previously disclosed to PTO
5,189,507	previously disclosed to PTO
5,067,007	previously disclosed to PTO
4,893,172	previously disclosed to PTO
4,860,433	previously disclosed to PTO
4,793,814	previously disclosed to PTO
4,764,848	previously disclosed to PTO
4,705,205	previously disclosed to PTO
4,667,219	previously disclosed to PTO
4,418,857	previously disclosed to PTO
4,074,342	previously disclosed to PTO
3,616,532	previously disclosed to PTO

GROUP 4: PCT/US95/14844 filed 13 Nov 95

5,187,020 Kwon, et al.; 2/93 428/601
COMPLIANT CONTACT PAD

4,983,907 Crowley; 1/91 324/158 P
DRIVEN GUARD PROBE CARD

5,148,103 Pasiecznik, Jr.; 9/92 324/158 P
APPARATUS FOR TESTING INTEGRATED CIRCUITS

5,471,151 DiFrancesco; 11/95 324/757
ELECTRICAL INTERCONNECT USING PARTICLE ENHANCED JOINING OF
METAL SURFACES

3,832,632 Ardezzone; 8/74 324/158 P
MULTI-POINT PROBE HEAD ASSEMBLY

GROUP 5: PCT/US95/14885 filed 15 Nov 95

4,983,907 Crowley; 1/91 324/158 P
DRIVEN GUARD PROBE CARD

5,055,780 Takagi, et al.; 10/91 324/158 F
PROBE PLATE USED FOR TESTING A SEMICONDUCTOR DEVICE, AND A
TEST APPARATUS THEREFOR

5,187,020 Kwon, et al.; 2/93 428/601
COMPLIANT CONTACT PAD

GROUP 6: Other References of Interest

5,525,545 Grube, et al.; 6/96 437/209
SEMICONDUCTOR CHIP ASSEMBLIES AND COMPONENTS WITH PRESSURE
CONTACTS

5,518,964 DiStefano, et al.; 5/96 437/209
MICROELECTRONIC MOUNTING WITH MULTIPLE LEAD DEFORMATION AND
BONDING

5,491,302 DiStefano, et al.; 2/96 114/260
MICROELECTRONIC BONDING WITH LEAD MOTION

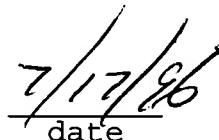
5,489,749 DiStefano, et al.; 2/96 174/261
SEMICONDUCTOR CONNECTION COMPONENTS AND METHOD WITH RELEASABLE
LEAD SUPPORT

5,477,611 Sweis, et al.; 12/95 29/840
METHOD OF FORMING INTERFACE BETWEEN DIE AND CHIP CARRIER

5,455,390 DiStefano, et al.; 10/95 174/262
MICROELECTRONICS UNIT MOUNTING WITH MULTIPLE LEAD BONDING

For the Applicant,


Gerald E. Linden 30,282
(407) 382-7966


date
7/17/96

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